Laser Assisted Particle Removal

Chemical Mechanisms

- Photochemical reactive removal
- Photo— + thermo chemical reactive removal

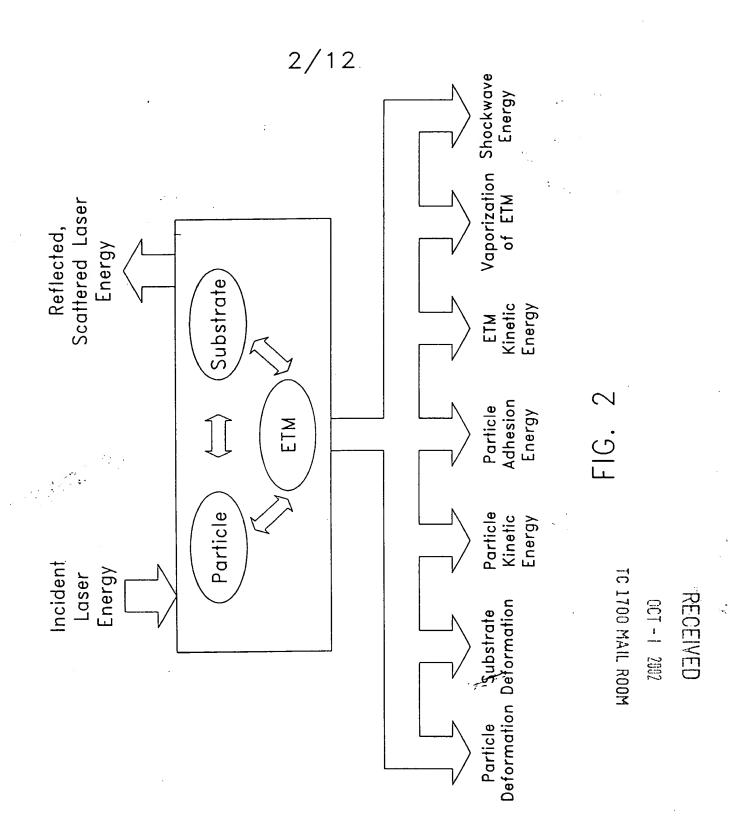
FIG.

Mechanical Mechanisms

- Particle deformation_
- Substrate 280 PC deformation 8
- Energy transfer medium explosive evaporation

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Substrate without ETM	Rapid thermal expansion of the substrate	λ>>Particle Diameter or λ <particle diameter<br="">if α_{particle} is low</particle>	High α _{substrate}	Melting/Ablation of particle or substrate	Φ _{th} =0.02-0.3 J/cm ² I _{th} =1-30 MW/cm ² t=7-30 ns
Substrate with ETM	Microbubble formation at liquid/solid interface	λ>Particle Diameter	High α _{substrate}	-Melting/Ablation of particle or substrate -Shockwave in ETM	Φ _{th} =0.02-0.3 J/cm ² I _{th} =2-600 MW/cm ² t=0.03-20 ns
ЕТМ	Explosive evaporation of ETM	λ>>Particle Diameter	High α _{ETM}	Shockwave, substrate absorption	Φ _{th} =0.65-2.2 J/cm ² I _{th} =3-11 MW/cm ²
Particle	Rapid thermal expansion of particle	λ< <particle diameter<="" td=""><td>α_{particle} >> αsubstrate</td><td>-Melting/Ablation of particle</td><td>th =0.01-0.08 J/cm² l_{th} =1-11 MW/cm² D=20 Jm</td></particle>	α _{particle} >> αsubstrate	-Melting/Ablation of particle	th =0.01-0.08 J/cm ² l _{th} =1-11 MW/cm ² D=20 Jm
Absorption Medium	Removal Mechanism	wavelength	Energy Absorption	Substrate Damage	Particle Removal Threshold

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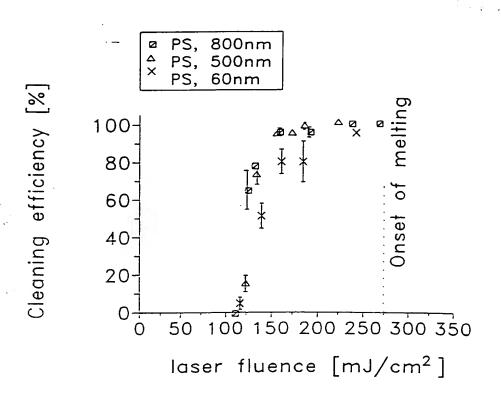


FIG. 4

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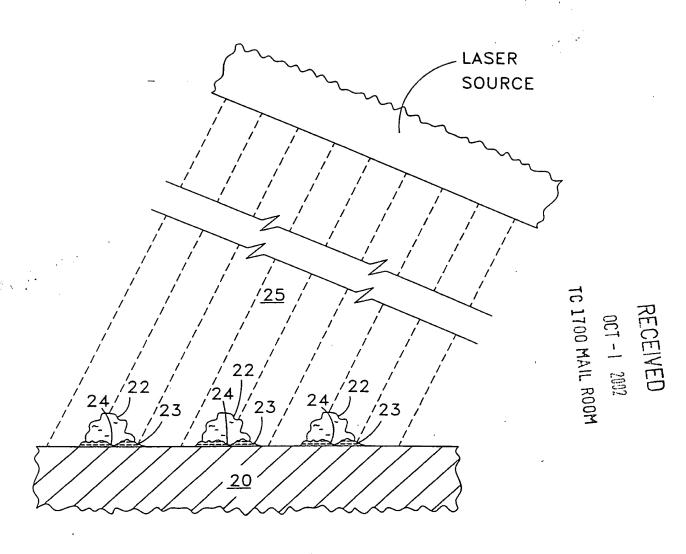


FIG. 5

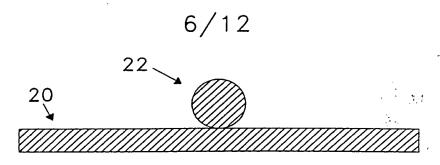


FIG. 6A

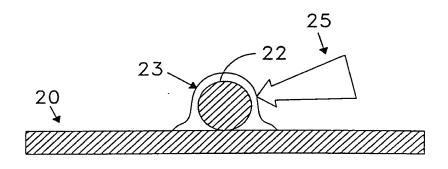


FIG. 6B

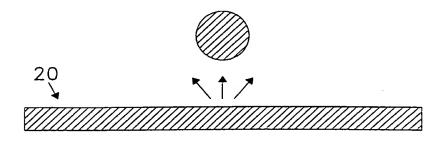


FIG. 6C

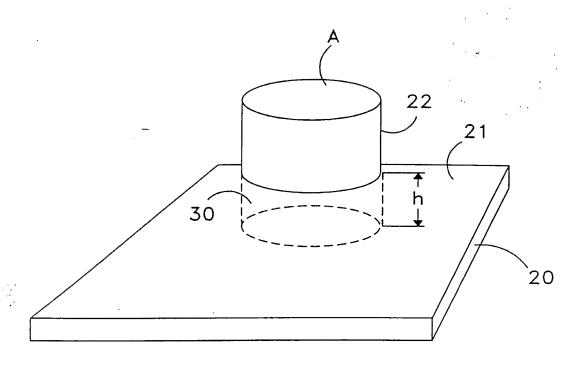


FIG. 7

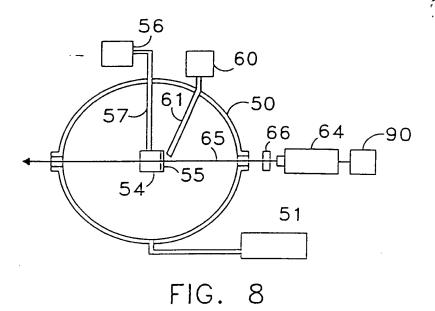


FIG. 9

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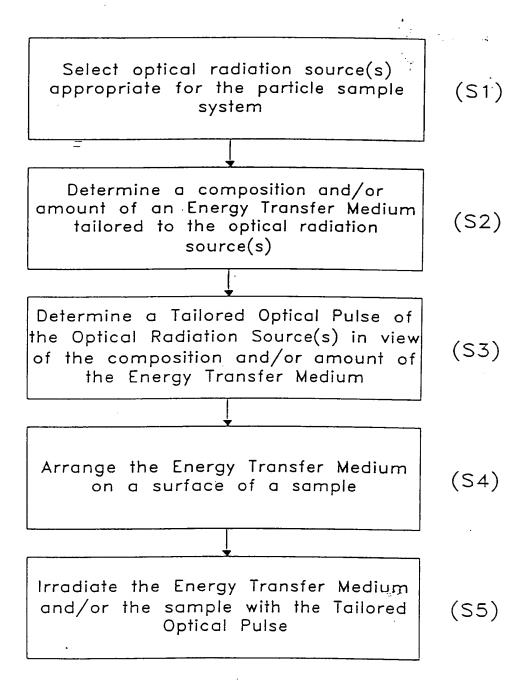


FIG. 10

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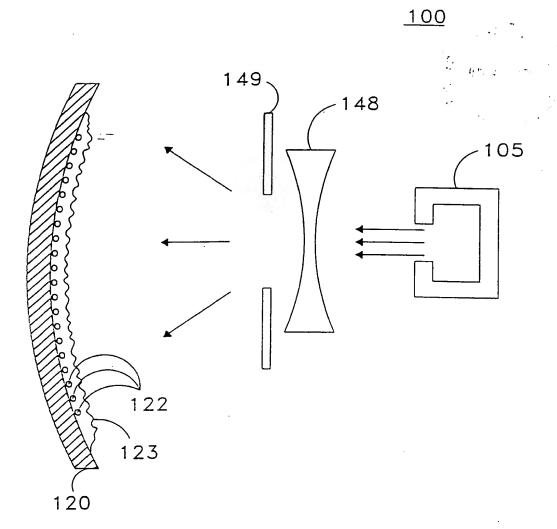


FIG. 11



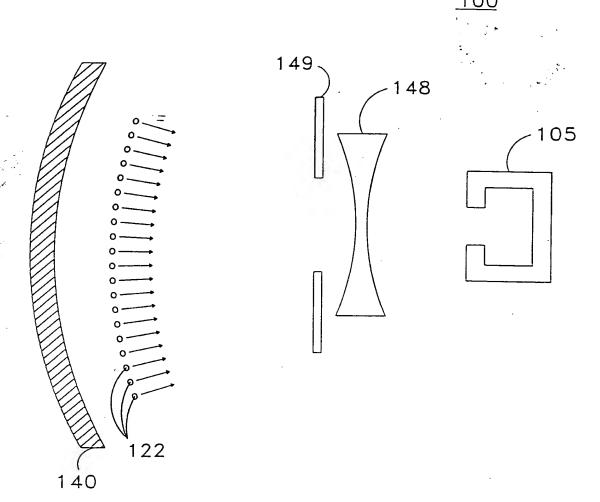


FIG. 12



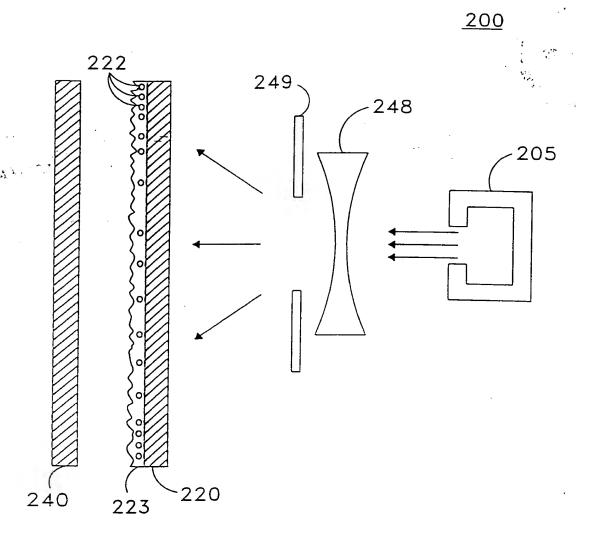


FIG. 13